Tool ID: 208
Tool Location: 107

Equipment Information Sheet

PT770 Etcher - Left Side (Metal Etch)

Manager: Tom Pennell 607-254-4309
Backup: Jeremy Clark 607-254-6487

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- Chlorine and BCl3 chemistries used.

USAGE RESTRICTIONS

- User must remain in the lab when the tool is in operation.
- If using resist mask, 5mm edge must be removed.

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 4 hour block reservations at any time. Max 12 hours reserved in advance per user. No consecutive research group reservations. Users may utilize any unreserved time.

MATERIALS COMPATIBILITY CATEGORY

Tool Category 3: Silcion, III-V Compound Semiconductor, Glass and Metal Category

Allowed	Not Allowed
Tool category 1/1E and 2 materials	Glass Substrates
III/V compound Semiconductors allowed	No CNF Class A or Class B metals-and oxides/compounds of i.e. (Magnesium,Zinc, Barium, Calcium)
PECVD and ALD Films	No High Vapor pressure materials
Cured organics and baked Photoresist	
Organic/Bio Materials prepped w/o Salt Buffers	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- 4-inch wafers only.
- Photoresist mask - edge bead must be removed (5mm ring) if using 4-inch wafers
- Pieces should be mounted to sapphire wafer
- Do not change recipes without staff approval

Last Updated: 03/24/2021